

## Features

- Super Low Gate Charge
- 100% EAS Guaranteed
- Excellent CdV/dt effect decline
- Green Device Available
- Advanced high cell density Trench technology

## Product Summary

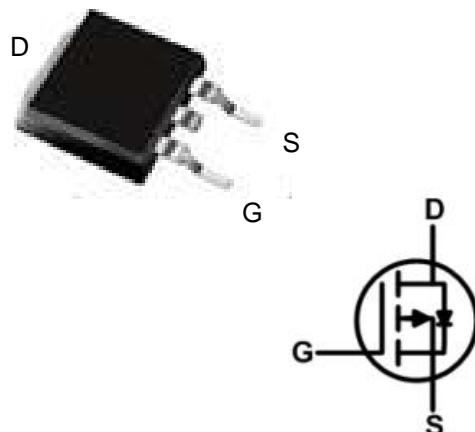
BVDSS	RDSON	ID
-60V	14mΩ	-60A

## Description

The D60P06M is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The D60P06M meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

## TO-252 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sub>1</sub>	-60	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sub>1</sub>	-35	A
I <sub>DM</sub>	Pulsed Drain Current <sub>2</sub>	-170	A
EAS	Single Pulse Avalanche Energy <sub>3</sub>	330	mJ
I <sub>AS</sub>	Avalanche Current	-40	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sub>4</sub>	90	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sub>1</sub>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sub>1</sub>	---	1.4	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-60	---	---	V
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sub>2</sub>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-18A	---	---	14	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-12A	---	---	17	
V <sub>GTH</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	---	-2.5	V
△V <sub>GTH</sub>	V <sub>GTH</sub> Temperature Coefficient		---	4.28	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	-5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-18A	---	43	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	2.6	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-30V , V <sub>GS</sub> =-10V , I <sub>D</sub> =-12A	---	85	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	11	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	30	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-30V , V <sub>GS</sub> =-10V , R <sub>G</sub> =6Ω, I <sub>D</sub> =-1A	---	18	---	ns
T <sub>r</sub>	Rise Time		---	12	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	100	---	
T <sub>f</sub>	Fall Time		---	68	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-30V , V <sub>GS</sub> =0V , f=1MHz	---	4635	---	pF
C <sub>oss</sub>	Output Capacitance		---	524	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	241	---	

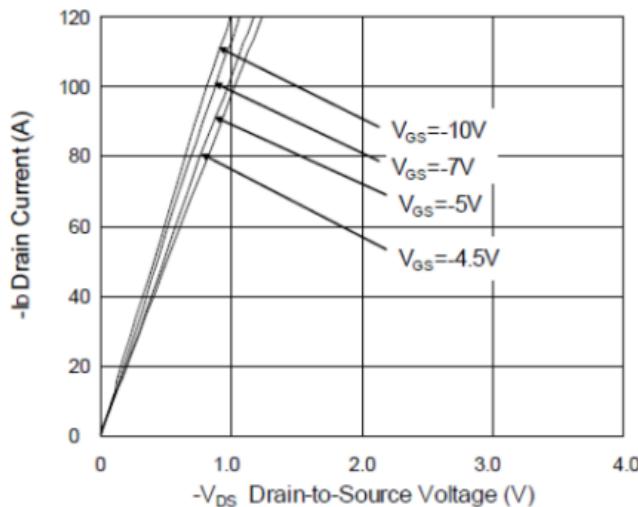
**Diode Characteristics**

I <sub>s</sub>	Continuous Source Current <sub>1,5</sub>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-40	A
V <sub>SD</sub>	Diode Forward Voltage <sub>2</sub>	V <sub>GS</sub> =0V , I <sub>s</sub> =-1A , T <sub>J</sub> =25°C	---	---	-1.2	V

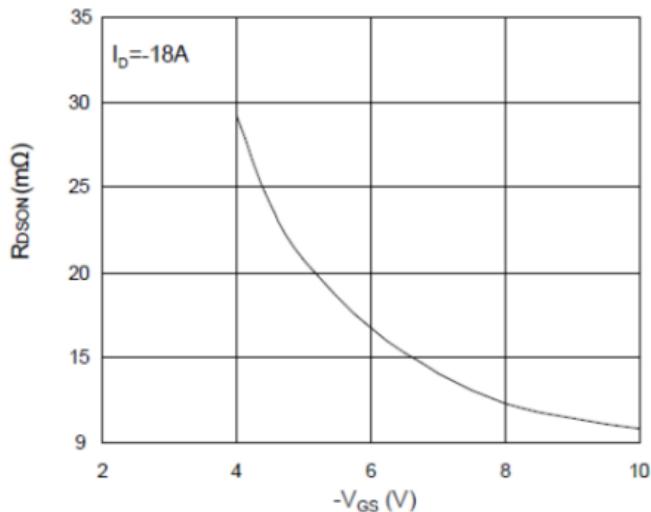
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-30V,V<sub>GS</sub>=-10V,L=0.5mH,I<sub>AS</sub>=-40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>s</sub> , in real applications , should be limited by total power dissipation.

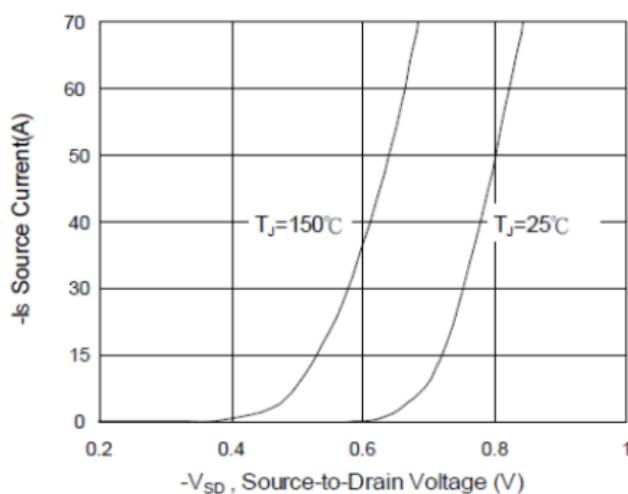
### Typical Characteristics



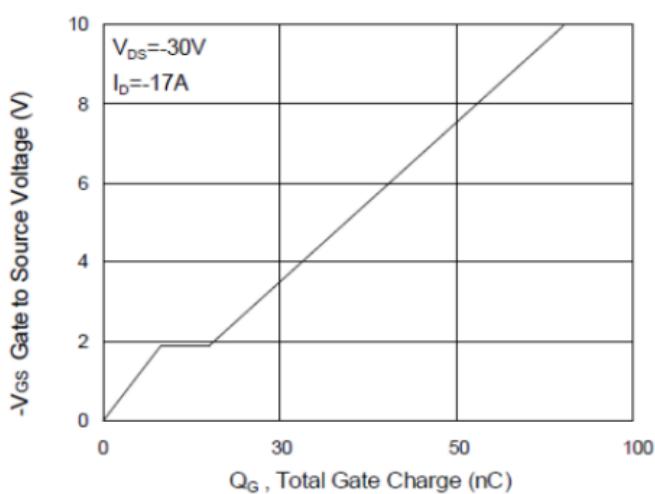
**Fig.1 Typical Output Characteristics**



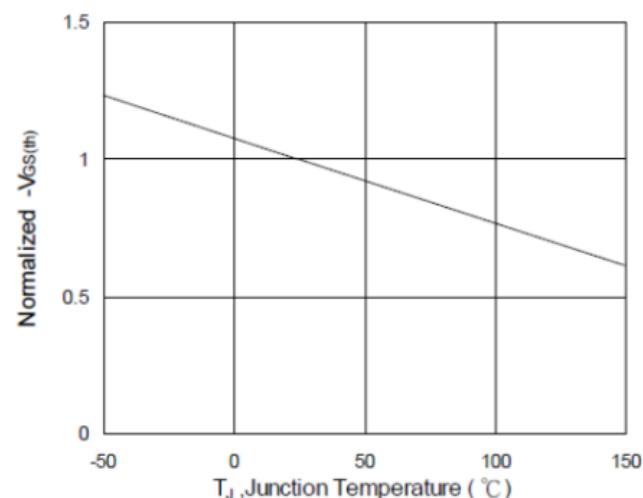
**Fig.2 On-Resistance v.s Gate-Source**



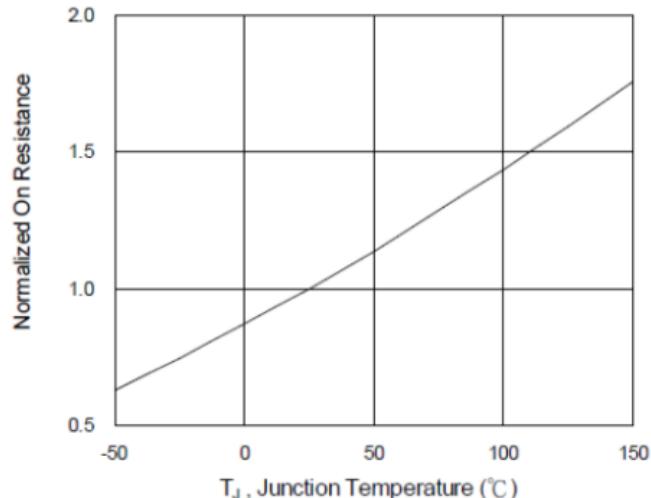
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

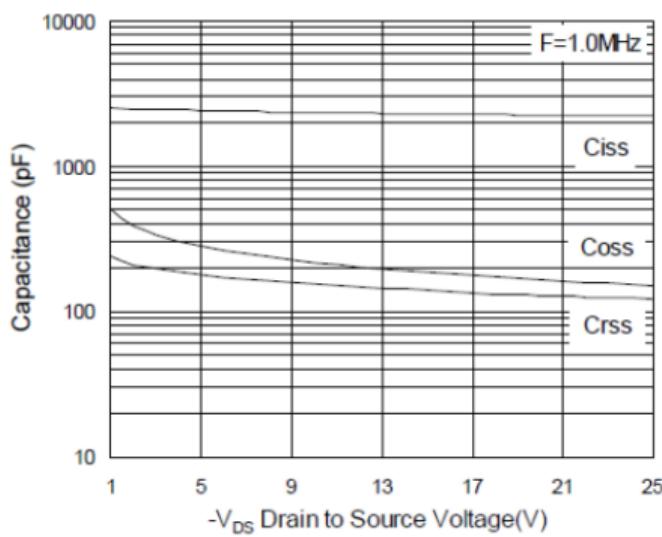


Fig.7 Capacitance

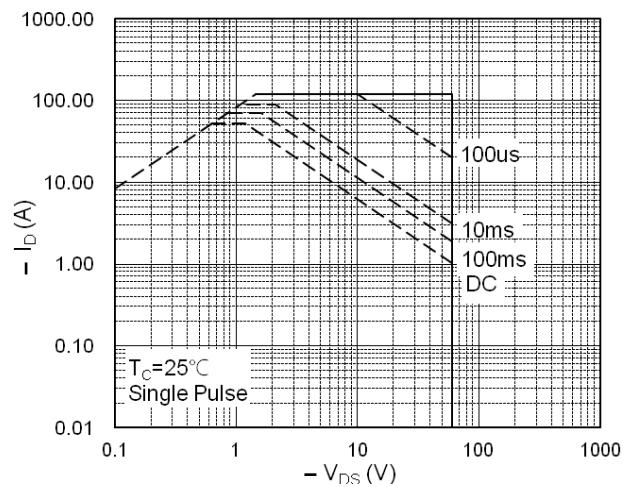


Fig.8 Safe Operating Area

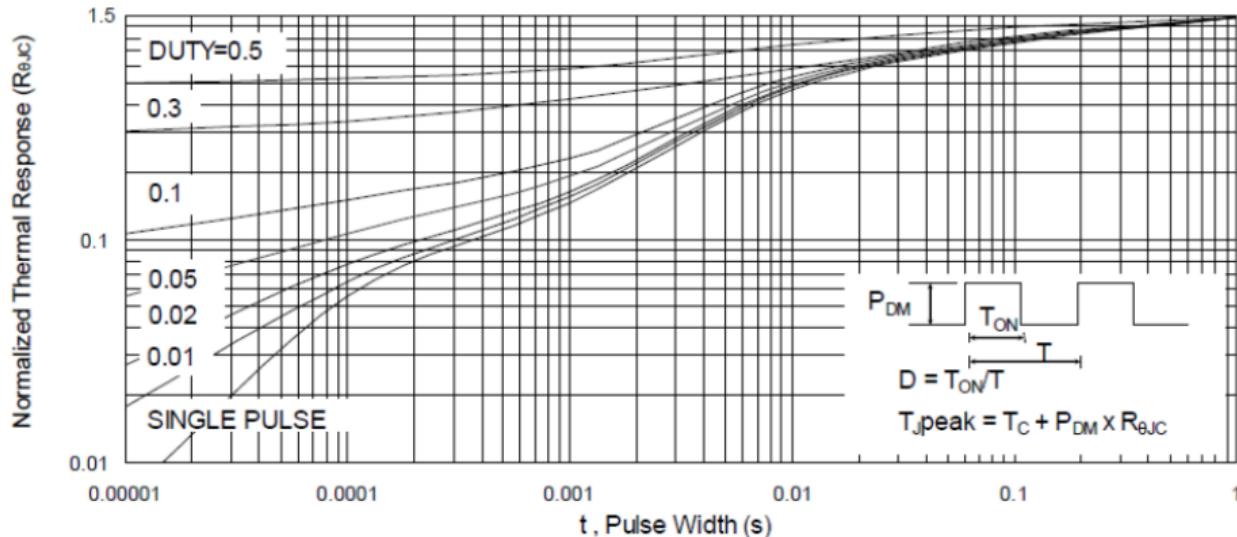


Fig.9 Normalized Maximum Transient Thermal Impedance

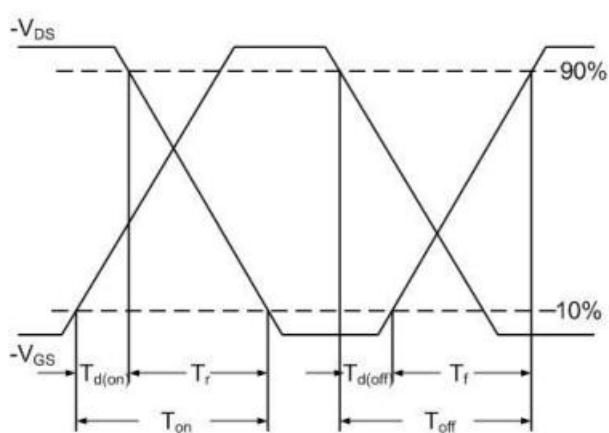


Fig.10 Switching Time Waveform

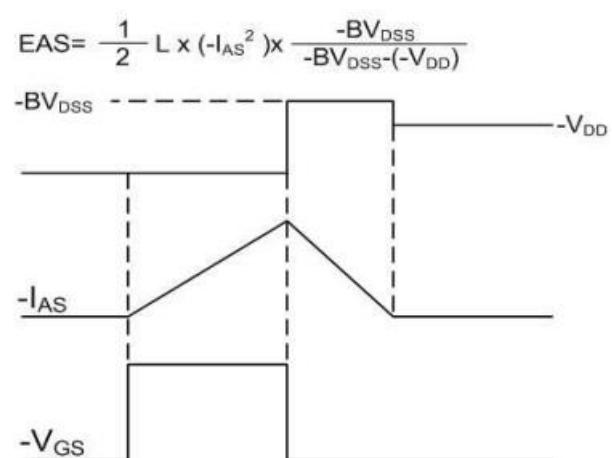
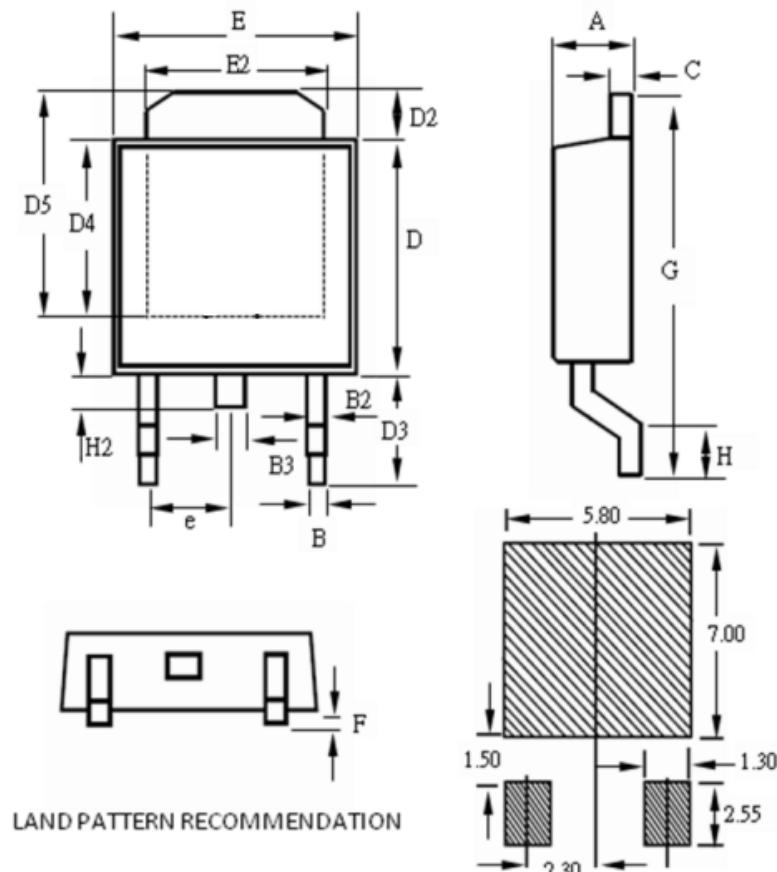


Fig.11 Unclamped Inductive Waveform

## TO-252 Package Outline



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.10	--	2.50	0.083	--	0.098
B	0.30	--	0.89	0.012	--	0.035
B2	0.40	--	1.14	0.016	--	0.045
B3	0.60	--	1.00	0.024	--	0.039
C	0.40	--	0.89	0.016	--	0.035
D	5.30	--	6.25	0.209	--	0.246
D2	0.50	--	1.70	0.020	--	0.067
D3	2.20	--	3.40	0.087	--	0.134
D4	4.32	--	--	0.170	--	--
D5	5.21	--	--	0.205	--	--
E	6.30	--	6.73	0.248	--	0.265
E2	4.80	--	5.46	0.189	--	0.215
F	0.00	--	0.30	0.000	--	0.012
G	9.20	--	10.41	0.362	--	0.410
H	0.90	--	1.95	0.035	--	0.077
H2	0.50	--	1.10	0.020	--	0.043
e	--	2.30	--	--	0.091	--

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